FAIRCHILD SEMICONDUCTOR®

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# MM74HC688
# 8-Bit Magnitude Comparator (Equality Detector)

## General Description

The MM74HC688 equality detector utilizes advanced silicon-gate CMOS technology to compare bit for bit two 8-bit words and indicates whether or not they are equal. The $\overline{P}$=$\overline{Q}$ output indicates equality when it is LOW. A single active low enable is provided to facilitate cascading of several packages and enable comparison of words greater than 8 bits.

This device is useful in memory block decoding applications, where memory block enable signals must be generated from computer address information.

The comparator's output can drive 10 low power Schottky equivalent loads. This comparator is functionally and pin compatible to the 74LS688. All inputs are protected from damage due to static discharge by diodes to $V_{CC}$ and ground.

## Features

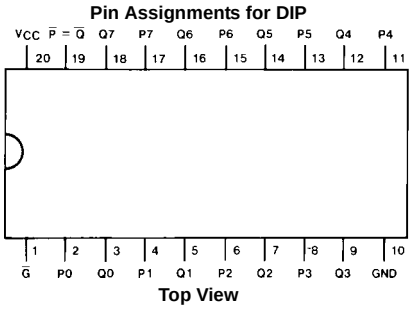
- Typical propagation delay: 20 ns
- Wide power supply range: 2–6V
- Low quiescent current: 80 μA (74 Series)
- Large output current: 4 mA (74 Series)
- Same as HC521

## Ordering Code:

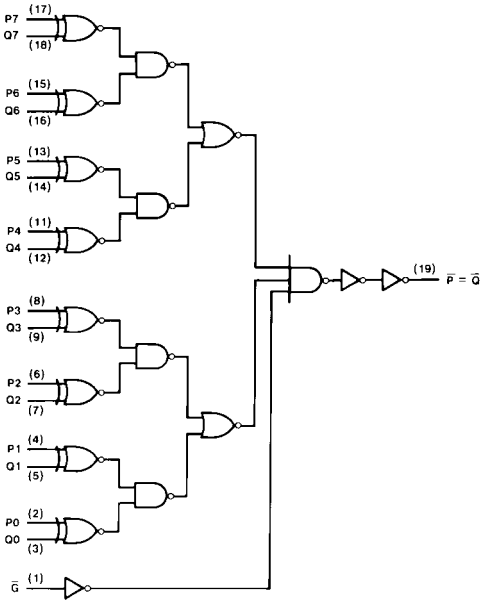
| Order Number | Package Number | Package Description |
|---|---|---|
| MM74HC688WM | M20B | 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide |
| MM74HC688SJ | M20D | 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| MM74HC688MTC | MTC20 | 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |
| MM74HC688N | N20A | 20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide |

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

## Connection Diagram




## Logic Diagram




## Truth Table

| Inputs | | |
|---|---|---|
| Data | Enable | |
| P,Q | $\overline{G}$ | $\overline{P} = \overline{Q}$ |
| P = Q | L | L |
| P > Q | L | H |
| P < Q | L | H |
| X | H | H |

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## Absolute Maximum Ratings(Note 1)

(Note 2)

| | |
|---|---|
| Supply Voltage ($V_{CC}$) | −0.5 to +7.0V |
| DC Input Voltage ($V_{IN}$) | −1.5 to $V_{CC}$ +1.5V |
| DC Output Voltage ($V_{OUT}$) | −0.5 to $V_{CC}$ +0.5V |
| Clamp Diode Current ($I_{IK}$, $I_{OK}$) | ±20 mA |
| DC Output Current, per pin ($I_{OUT}$) | ±25 mA |
| DC $V_{CC}$ or GND Current, per pin ($I_{CC}$) | ±50 mA |
| Storage Temperature Range ($T_{STG}$) | −65°C to +150°C |
| Power Dissipation ($P_D$) | |
| (Note 3) | 600 mW |
| S.O. Package only | 500 mW |
| Lead Temperature ($T_L$) | |
| (Soldering 10 seconds) | 260°C |

## Recommended Operating Conditions

| | Min | Max | Units |
|---|---|---|---|
| Supply Voltage ($V_{CC}$) | 2 | 6 | V |
| DC Input or Output Voltage ($V_{IN}$, $V_{OUT}$) | 0 | $V_{CC}$ | V |
| Operating Temperature Range ($T_A$) | −40 | +85 | °C |
| Input Rise or Fall Times | | | |
| ($t_r$, $t_f$) $V_{CC}$ = 2.0V | | 1000 | ns |
| $V_{CC}$ = 4.5V | | 500 | ns |
| $V_{CC}$ = 6.0V | | 400 | ns |

**Note 1:** Absolute Maximum Ratings are those values beyond which damage to the device may occur.

**Note 2:** Unless otherwise specified all voltages are referenced to ground.

**Note 3:** Power Dissipation temperature derating — plastic "N" package: −12 mW/°C from 65°C to 85°C.

## DC Electrical Characteristics (Note 4)

| Symbol | Parameter | Conditions | $V_{CC}$ | $T_A$ = 25°C | $T_A$ = −40 to 85°C | $T_A$ = −55 to 125°C | Units |
|---|---|---|---|---|---|---|---|
| | | | | Typ | Guaranteed Limits | | |
| $V_{IH}$ | Minimum HIGH Level Input Voltage | | 2.0V | | 1.5 | 1.5 | 1.5 | V |
| | | | 4.5V | | 3.15 | 3.15 | 3.15 | V |
| | | | 6.0V | | 4.2 | 4.2 | 4.2 | V |
| $V_{IL}$ | Maximum LOW Level Input Voltage | | 2.0V | | 0.5 | 0.5 | 0.5 | V |
| | | | 4.5V | | 1.35 | 1.35 | 1.35 | V |
| | | | 6.0V | | 1.8 | 1.8 | 1.8 | V |
| $V_{OH}$ | Minimum HIGH Level Output Voltage | $V_{IN}$ = $V_{IH}$ or $V_{IL}$ | | | | | | |
| | | $\|I_{OUT}\| \leq 20\ \mu A$ | 2.0V | 2.0 | 1.9 | 1.9 | 1.9 | V |
| | | | 4.5V | 4.5 | 4.4 | 4.4 | 4.4 | V |
| | | | 6.0V | 6.0 | 5.9 | 5.9 | 5.9 | V |
| | | $V_{IN}$ = $V_{IH}$ or $V_{IL}$ | | | | | | |
| | | $\|I_{OUT}\| \leq 4.0$ mA | 4.5V | 4.2 | 3.98 | 3.84 | 3.7 | V |
| | | $\|I_{OUT}\| \leq 5.2$ mA | 6.0V | 5.7 | 5.48 | 5.34 | 5.2 | V |
| $V_{OL}$ | Maximum LOW Level Output Voltage | $V_{IN}$ = $V_{IH}$ or $V_{IL}$ | | | | | | |
| | | $\|I_{OUT}\| \leq 20\ \mu A$ | 2.0V | 0 | 0.1 | 0.1 | 0.1 | V |
| | | | 4.5V | 0 | 0.1 | 0.1 | 0.1 | V |
| | | | 6.0V | 0 | 0.1 | 0.1 | 0.1 | V |
| | | $V_{IN}$ = $V_{IH}$ or $V_{IL}$ | | | | | | |
| | | $\|I_{OUT}\| \leq 4.0$ mA | 4.5V | 0.2 | 0.26 | 0.33 | 0.4 | V |
| | | $\|I_{OUT}\| \leq 5.2$ mA | 6.0V | 0.2 | 0.26 | 0.33 | 0.4 | V |
| $I_{IN}$ | Maximum Input Current | $V_{IN}$ = $V_{CC}$ or GND | 6.0V | | ±0.1 | ±1.0 | ±1.0 | μA |
| $I_{CC}$ | Maximum Quiescent Supply Current | $V_{IN}$ = $V_{CC}$ or GND | 6.0V | | 8.0 | 80 | 160 | μA |
| | | $I_{OUT}$ = 0 μA | | | | | | |

**Note 4:** For a power supply of 5V ±10% the worst case output voltages ($V_{OH}$, and $V_{OL}$) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case $V_{IH}$ and $V_{IL}$ occur at $V_{CC}$ = 5.5V and 4.5V respectively. (The $V_{IH}$ value at 5.5V is 3.85V.) The worst case leakage current ($I_{IN}$, $I_{CC}$, and $I_{OZ}$) occur for CMOS at the higher voltage and so the 6.0V values should be used.

## AC Electrical Characteristics

$V_{CC}$ = 5V, $T_A$ = 25°C, $C_L$ = 15 pF, $t_r$ = $t_f$ = 6 ns

| Symbol | Parameter | Conditions | Typ | Guaranteed Limit | Units |
|---|---|---|---|---|---|
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay, any P or Q to Output | | 21 | 30 | ns |
| $t_{PLH}$, $t_{PHL}$ | Maximum Propagation Delay, Enable to any Output | | 14 | 20 | ns |

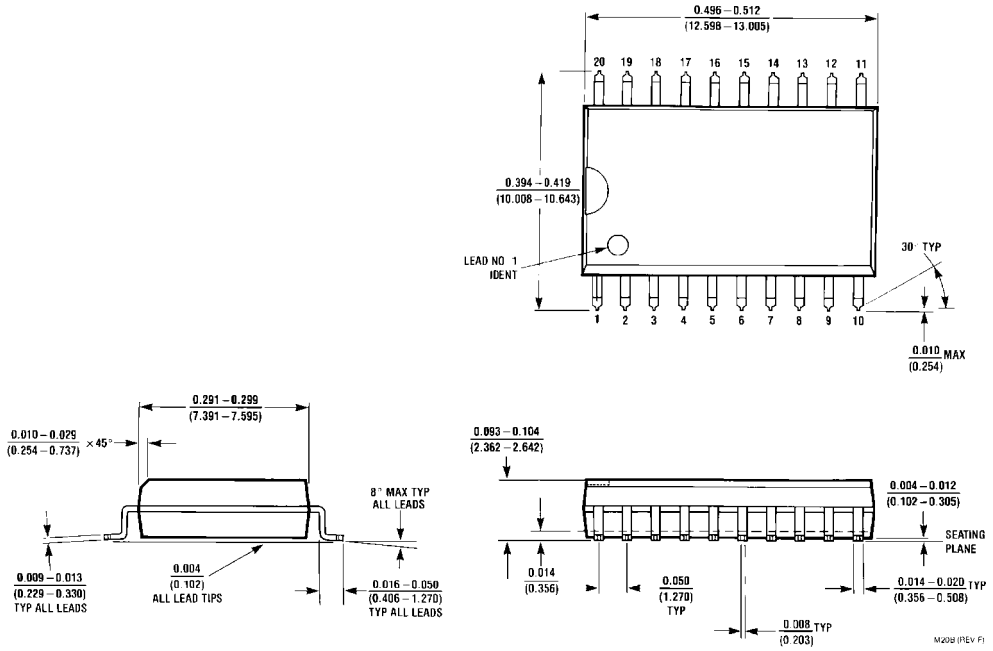
## AC Electrical Characteristics

$V_{CC}$ = 2.0V to 6.0V, $C_L$ = 50 pF, $t_r$ = $t_f$ = 6 ns (unless otherwise specified)

| Symbol | Parameter | Conditions | $V_{CC}$ | $T_A$ = 25°C | $T_A$ = −40 to 85°C | $T_A$ = −55 to 125°C | | Units |
|---|---|---|---|---|---|---|---|---|
| | | | | Typ | Guaranteed Limits | | | |
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay, P or Q to Output | | 2.0V | 60 | 175 | 220 | 263 | ns |
| | | | 4.5V | 22 | 35 | 44 | 53 | ns |
| | | | 6.0V | 19 | 30 | 38 | 45 | ns |
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay, Enable to Output | | 2.0V | 45 | 120 | 150 | 180 | ns |
| | | | 4.5V | 15 | 24 | 30 | 36 | ns |
| | | | 6.0V | 13 | 20 | 25 | 30 | ns |
| $t_{THL}$, $t_{TLH}$ | Maximum Output Rise and Fall Time | | 2.0V | 30 | 75 | 95 | 110 | ns |
| | | | 4.5V | 8 | 15 | 19 | 22 | ns |
| | | | 6.0V | 7 | 13 | 16 | 19 | ns |
| $C_{PD}$ | Power Dissipation Capacitance (Note 5) | | | 45 | | | | pF |
| $C_{IN}$ | Maximum Input Capacitance | | | 5 | 10 | 10 | 10 | pF |

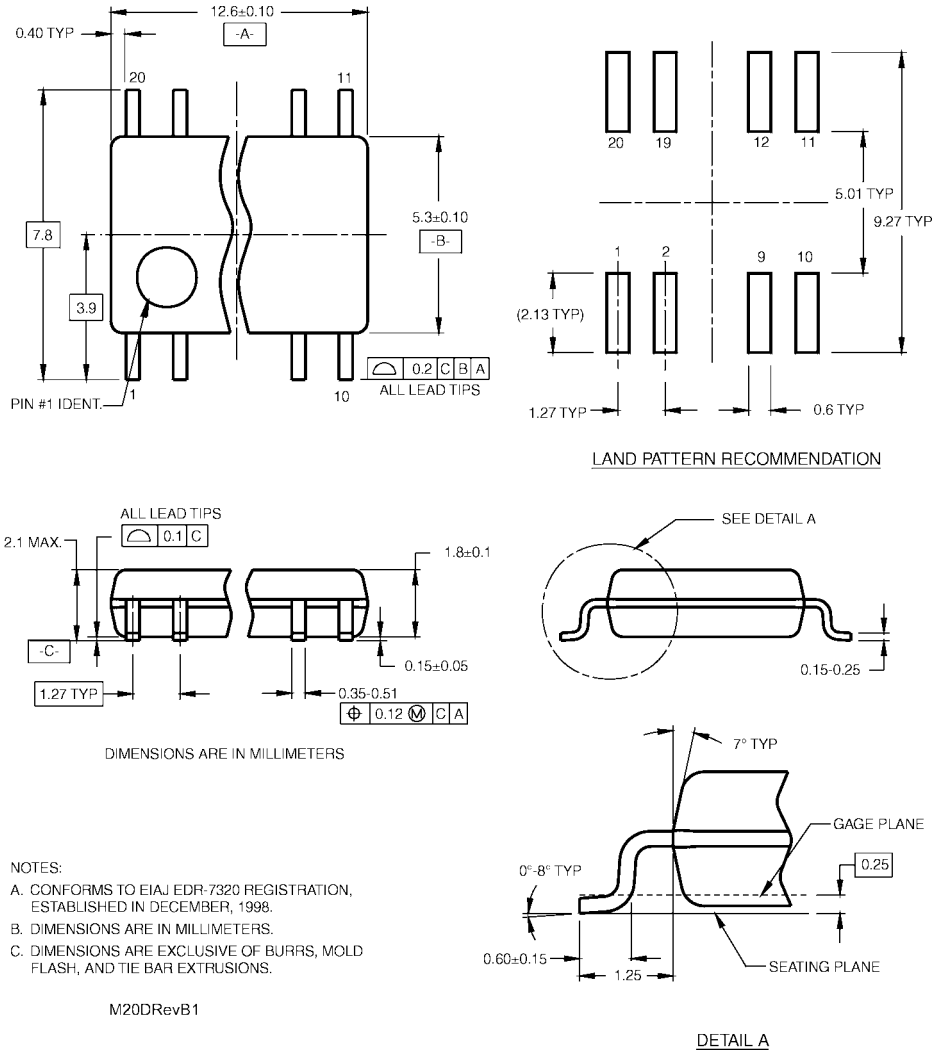
**Note 5:** $C_{PD}$ determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.

## Physical Dimensions inches (millimeters) unless otherwise noted




**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide**
**Package Number M20B**

## Physical Dimensions inches (millimeters) unless otherwise noted (Continued)




NOTES:

A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.

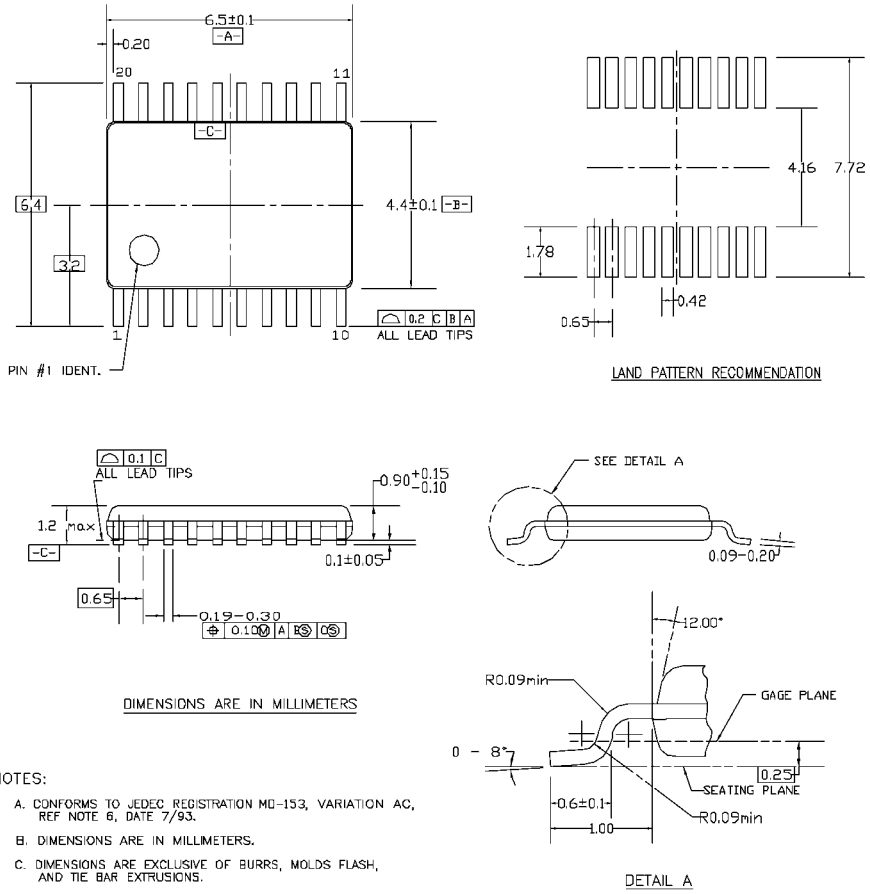
B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DRevB1

**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide**
**Package Number M20D**

## Physical Dimensions inches (millimeters) unless otherwise noted (Continued)




NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.

B. DIMENSIONS ARE IN MILLIMETERS.

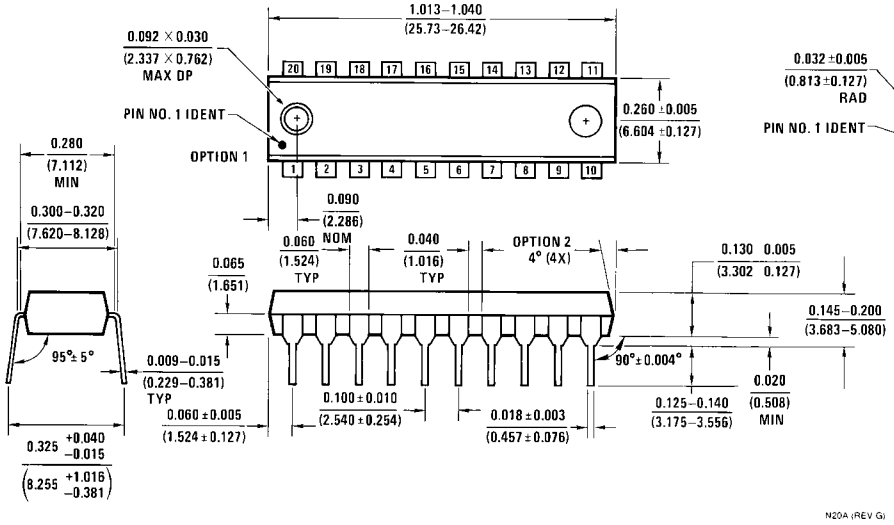
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.

D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REVD1

**20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide**
**Package Number MTC20**

## Physical Dimensions inches (millimeters) unless otherwise noted (Continued)




**20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide**
**Package Number N20A**

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